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Substitute for form 1449A/PTO					A	pplication Number Filed Herewith				
					F	Filing Date	November 17, 2003			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT						First Named Inventor:	Thomas Hantschel			
(use as many sheets as necessary)						Examiner name: unknown	GROUP: unknown			
Sheet	1 of			1		Attorney Docket Number	A3235 (XCP-035)			
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Examiner Initials*	Cited No. 1	U.S Numb		t Document  Kind Code <sup>2</sup> (if known)		lame of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY Pages, Columns, Lines Where Relevant Info.			
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)										
Despont et al.: "Wafer-Scale Microdevice Transfer/Interconnect: From A New Integration Method To Its Application In An AFM-Based Data-Storage System", 2003 IEEE, 12 <sup>th</sup> International Conference on Solid State Sensors, Actuators and Microsystems, Boston, June 8-12, 2003, pp. 1907-1910.  Wada et al.: "Fine Pitch Micro Probe Tips Using Thin Film Amorphous Alloy Under The Micromachining Fabrication Technology, Advantest Laboratories Ltd., Precision and Intelligence Laboratories, Tokyo Institute of										
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EXAMINER						DATE CONSIDERED				

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